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Dooley et al.

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(54) **STRUCTURE AND METHOD OF MANUFACTURE**

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See application file for complete search history.

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(57) **ABSTRACT**

A structure for a chemical sensing device, the structure comprising at least one electrically conductive element located in, and protruding from, at least one recess. A method of manufacturing the structure includes: (a) providing a template comprising at least one recess having a recess depth; (b) providing an electrically conductive material in the at least one recess; and (c) removing part of the template to decrease the recess depth of the at least one recess, thereby forming said protruding at least one electrically conductive element.

10 Claims, 5 Drawing Sheets

